

## 100V N-Channel MOSFET

### Product Summary

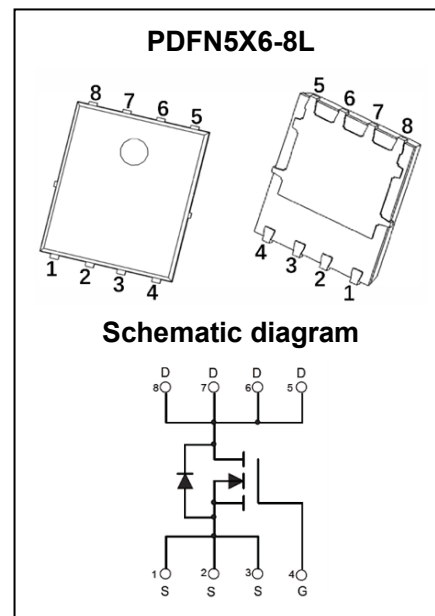
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
100V	6.2m $\Omega$ @10V	90A
	8.0m $\Omega$ @4.5V	

### Feature

- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

### Application

- Power Management
- Motor Driving
- High frequency switching, synchronous rectification



### Package Marking and Ordering Information

Part Number	Package	Marking	Packing	Reel Size	Tape Width	Qty
T062N10LNC	PDFN5X6-8L	T062N10L	Reel & Tape	330mm	12mm	5000pcs

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D$	$T_C = 25^\circ\text{C}$	90
		$T_C = 100^\circ\text{C}$	63
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	360	A
Single Pulsed Avalanche Current <sup>3</sup>	$I_{AS}$	32	A
Single Pulsed Avalanche Energy <sup>3</sup>	$E_{AS}$	256	mJ
Power Dissipation <sup>5</sup>	$P_D$	104	W
Thermal Resistance from Junction to Ambient <sup>6</sup>	$R_{\theta JA}$	56	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.2	$^\circ\text{C/W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>4</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.8	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$		6.2	8.0	$m\Omega$
		$V_{GS} = 4.5V, I_D = 15A$		8.0	10	$m\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 50V, V_{GS} = 0V, f = 1MHz$		1800		pF
Output Capacitance	$C_{oss}$			440		
Reverse Transfer Capacitance	$C_{rss}$			8.0		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		3.1		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 50V, V_{GS} = 10V, I_D = 20A$		32		nC
Gate-Source Charge	$Q_{gs}$			5.1		
Gate-Drain Charge	$Q_{gd}$			5.8		
Gate Plateau Voltage	$V_{plateau}$			2.9		V
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 50V, V_{GS} = 10V, R_G = 6\Omega, R_L = 2.5\Omega$		11		ns
Turn-On Rise Time	$t_r$			16		
Turn-Off Delay Time	$t_{d(off)}$			27		
Turn-Off Fall Time	$t_f$			20		
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 20A$			1.2	V
Diode Continuous Forward Current <sup>1</sup>	$I_S$	$T_C = 25^\circ\text{C}$			90	A
Diode Pulse Forward Current <sup>2</sup>	$I_{SM}$	$T_C = 25^\circ\text{C}$			360	A
Diode Reverse Recovery Time	$t_{rr}$	$I_F = 20A, di/dt = 100A/\mu s$		50		ns
Diode Reverse Recovery Charge	$Q_{rr}$	$I_F = 20A, di/dt = 100A/\mu s$		88		nC

Notes:

- 1.The maximum current rating is limited by package. And device mounted on a large heatsink.
- 2.Pulse Test: Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test: Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ . And device mounted on a large heatsink.
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

# Typical Characteristics

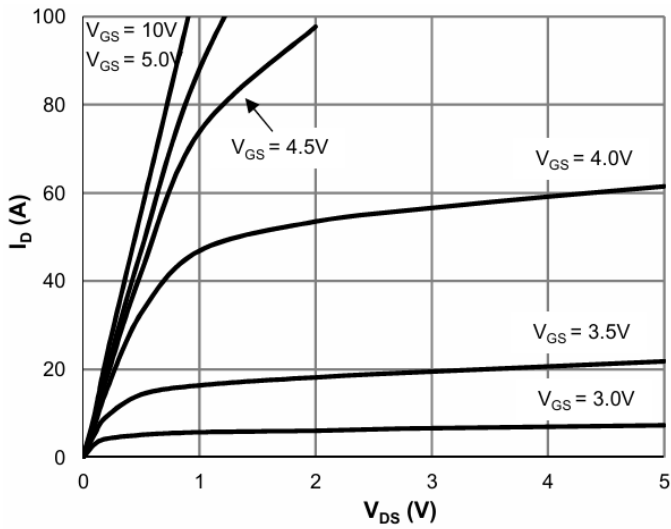


Figure 1: Saturation Characteristics

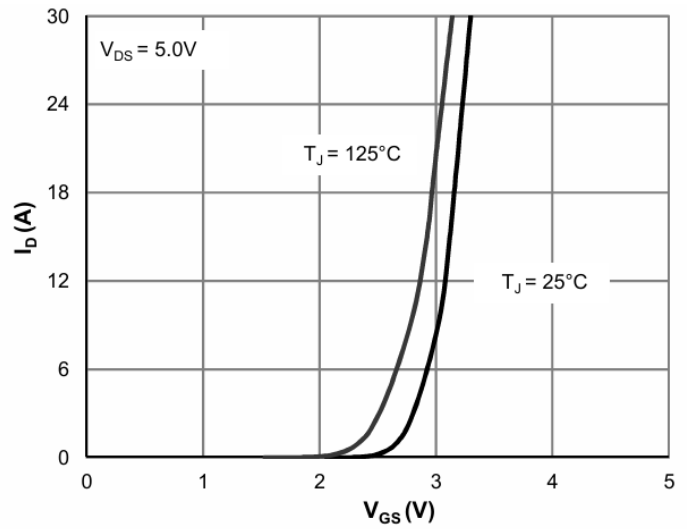


Figure 2: Transfer Characteristics

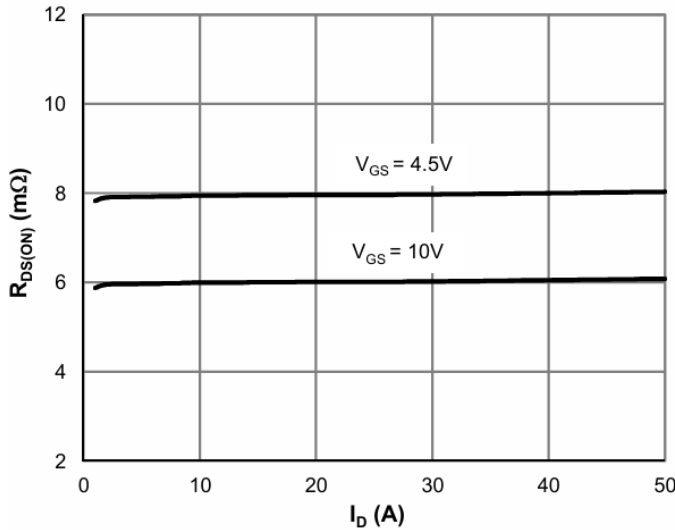


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

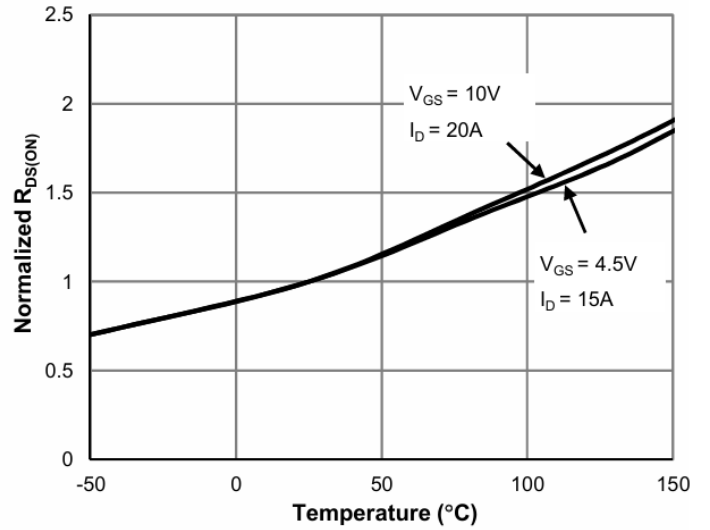


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

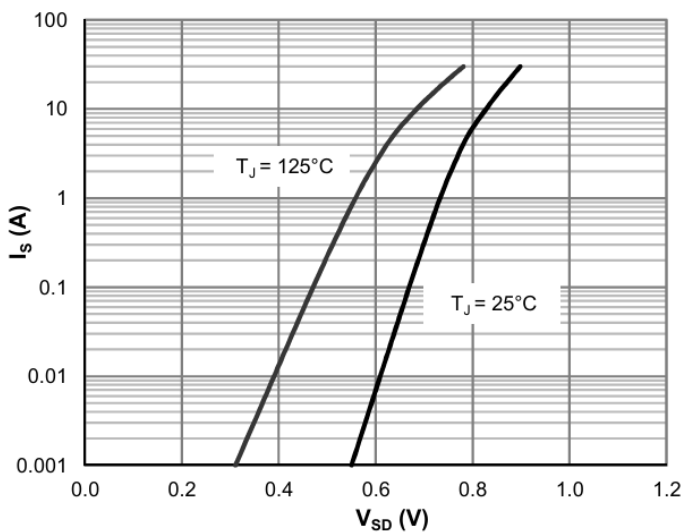


Figure 5: Body-Diode Characteristics

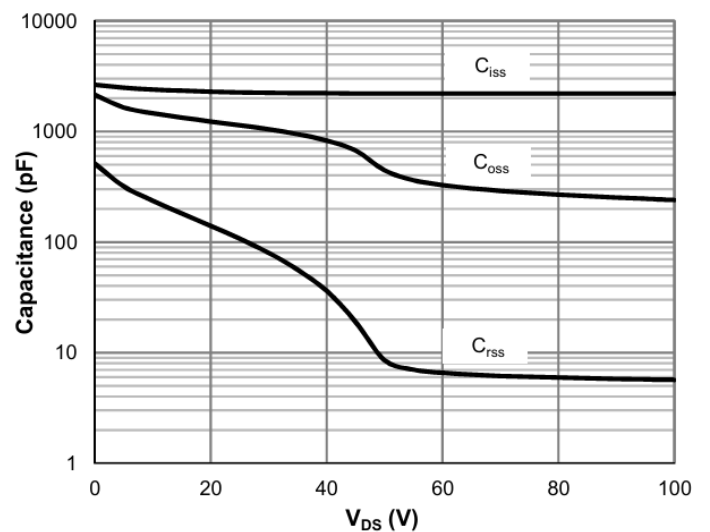


Figure 6: Capacitance Characteristics

# Typical Characteristics

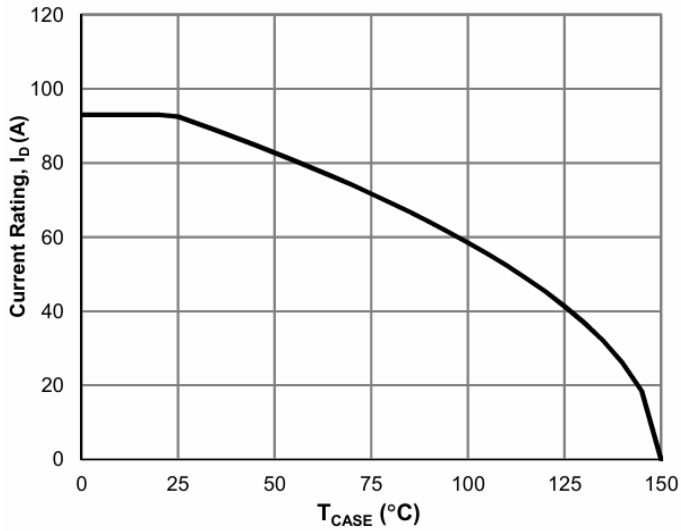


Figure 7: Current De-rating

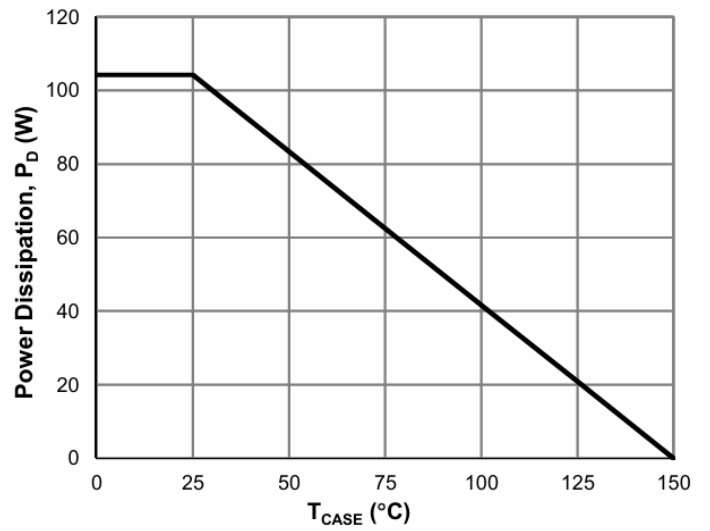


Figure 8: Power De-rating

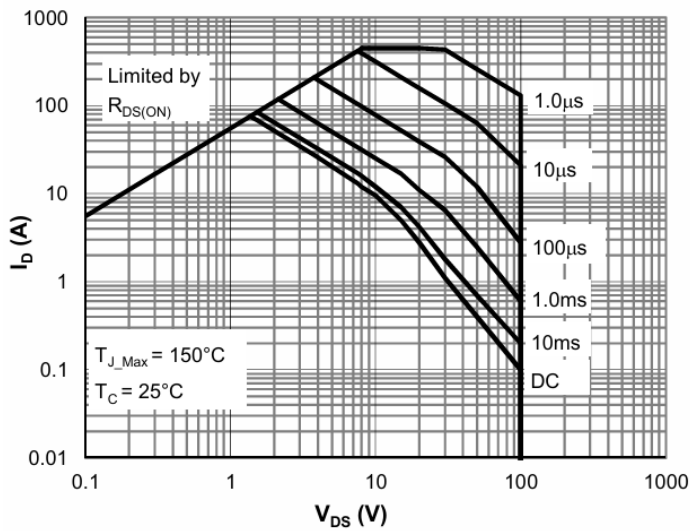


Figure 9: Maximum Safe Operating

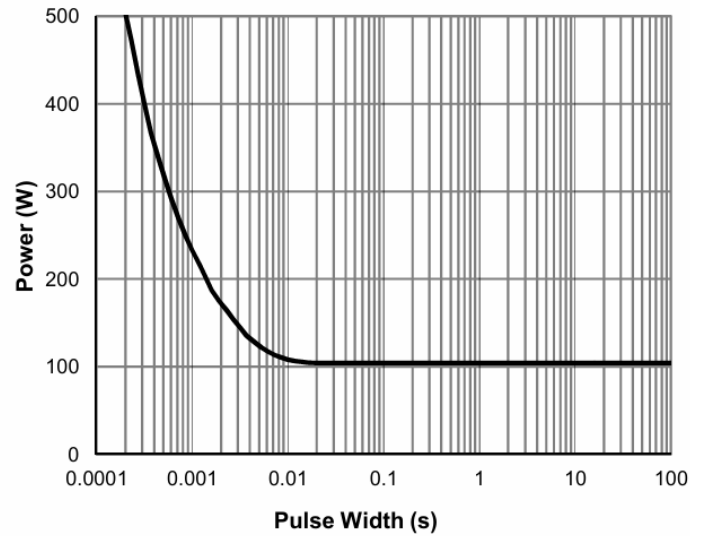


Figure 10: Single Pulse Power Rating, Junction-to-Case

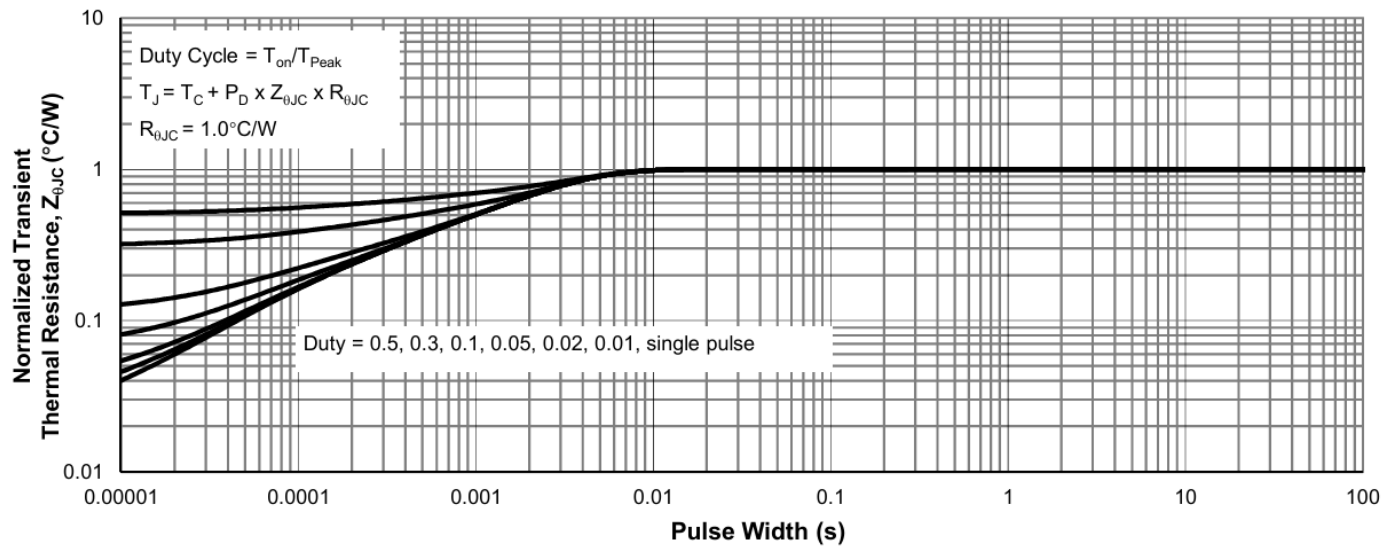
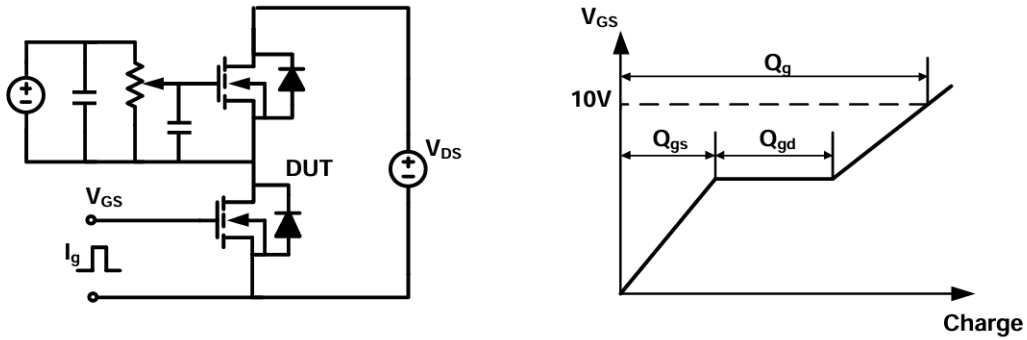
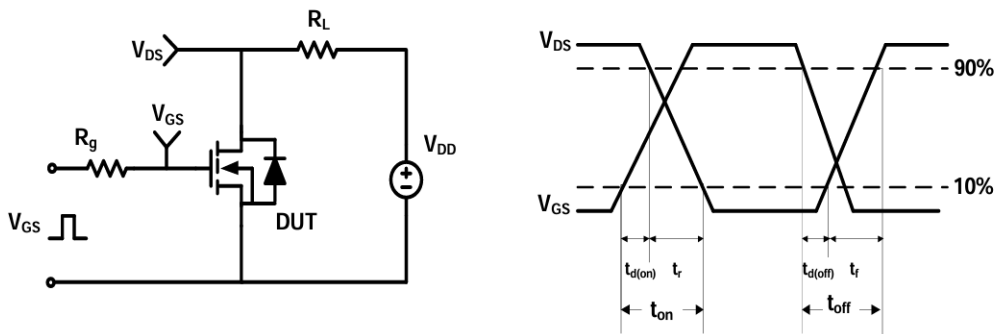


Figure 11: Normalized Maximum Transient Thermal Impedance

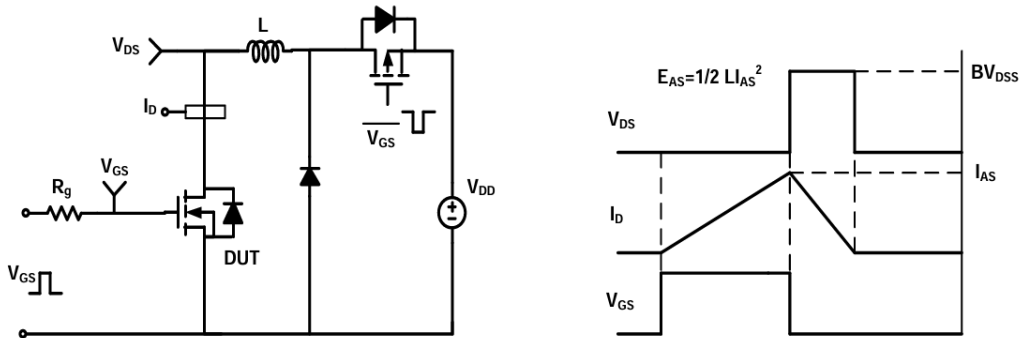
Gate Charge Test Circuit & Waveform



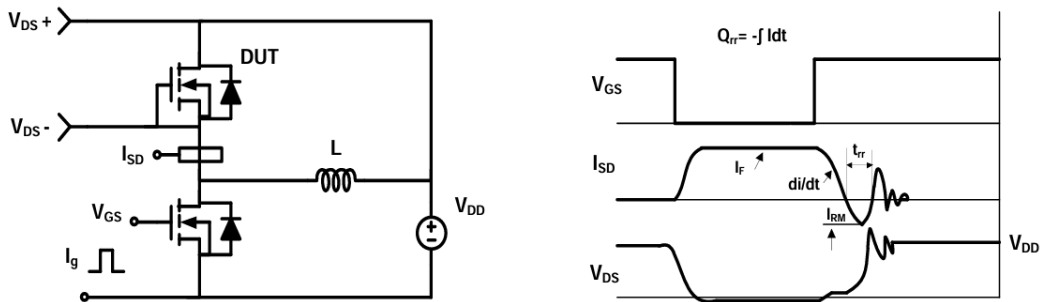
Resistive Switching Test Circuit & Waveform

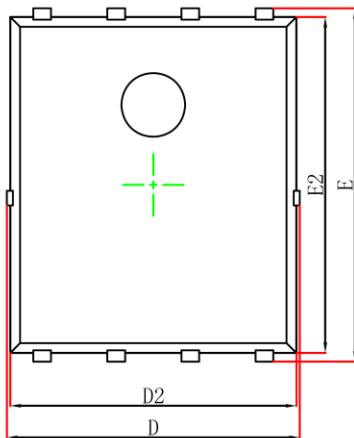


Unclamped Inductive Switching (UIS) Test Circuit & Waveform

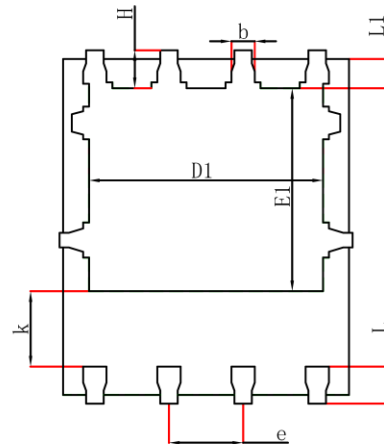


Diode Recovery Test Circuit & Waveform

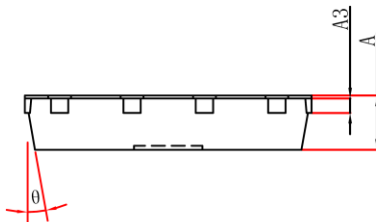




Top View  
[顶视图]



Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.10	0.035	0.043
A3	0.254REF		0.010REF	
D	4.700	5.260	0.185	0.207
E	5.750	6.250	0.226	0.246
D1	3.560	4.500	0.140	0.177
E1	3.180	3.660	0.125	0.144
D2	4.700	5.100	0.185	0.201
E2	5.600	6.000	0.220	0.236
k	1.100	-	0.043	-
b	0.300	0.500	0.012	0.020
e	1.270TYP		0.050TYP	
L	0.510	0.710	0.020	0.028
L1	0.424	0.576	0.017	0.023
H	0.510	0.710	0.020	0.028
$\theta$	8°	12°	8°	12°